

MOSFETs Silicon N-Channel MOS (DTMOSIV)

TK12E80W

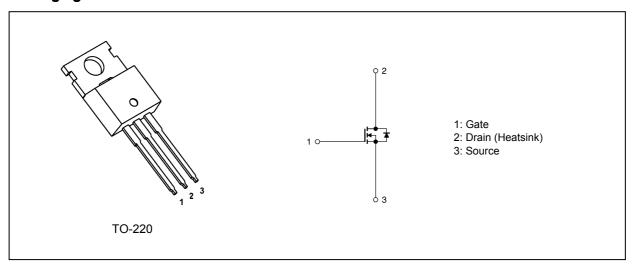
1. Applications

· Switching Voltage Regulators

2. Features

- (1) Low drain-source on-resistance: $R_{DS(ON)}$ = 0.38 Ω (typ.) by using Super Junction Structure : DTMOS
- (2) Easy to control Gate switching
- (3) Enhancement mode: V_{th} = 3.0 to 4.0 $V(V_{DS}$ = 10 V, I_{D} = 0.57 mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (Ta = 25 °C unless otherwise specified)

Characteristics			Symbol	Rating	Unit
Drain-source voltage			V_{DSS}	800	V
Gate-source voltage			V _{GSS}	±20	
Drain current (DC)	(Note	1)	I_D	11.5	Α
Drain current (pulsed)	(Note	1)	I _{DP}	46	
Power dissipation	(T _c = 25°C)		P_{D}	165	W
Single-pulse avalanche energy	(Note	2)	E _{AS}	326	mJ
Single-pulse avalanche current	,		I _{AS}	2.3	Α
Reverse drain current (DC)	(Note	1)	I_{DR}	11.5	
Reverse drain current (pulsed)	(Note	1)	I_{DRP}	46	
Channel temperature			T_ch	150	°C
Storage temperature			T _{stg}	-55 to 150	
Mounting torque			TOR	0.6	N · m

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).



5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal resistance	R _{th(ch-c)}	0.757	°C/W
Channel-to-ambient thermal resistance	R _{th(ch-a)}	83.3	

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: V_{DD} = 90 V, T_{ch} = 25 °C (initial), L = 112 mH, R_G = 25 Ω , I_{AS} = 2.3 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μΑ
Drain cut-off current	I _{DSS}	V _{DS} = 800 V, V _{GS} = 0 V	_	_	10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	800	_	_	V
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 0.57 mA	3.0	_	4.0	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 10 V, I _D = 5.8 A	_	0.38	0.45	Ω

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 300 V, V _{GS} = 0 V, f = 1 MHz	_	1400	_	pF
Reverse transfer capacitance	C _{rss}		_	3	_	
Output capacitance	C _{oss}		_	29	_	
Effective output capacitance	C _{o(er)}	V _{DS} = 0 to 640 V, V _{GS} = 0 V	_	35	_	
Gate resistance	r _g	V _{DS} = OPEN , f = 1 MHz	_	30	_	Ω
Switching time (rise time)	t _r	See Figure 6.2.1	_	40	_	ns
Switching time (turn-on time)	t _{on}		_	70	_	
Switching time (fall time)	t _f		_	11	_	
Switching time (turn-off time)	t _{off}		_	130	_	
MOSFET dv/dt ruggedness	dv/dt	$V_{DS} \le V_{(BR)DSS}$, $I_D \le 11.5 A$	50	_		V/ns

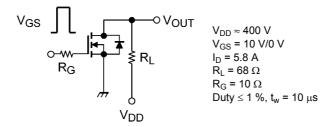


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx 640 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 11.5 \text{ A}$		23		nC
Gate-source charge 1	Q _{gs1}			8		
Gate-drain charge	Q_{gd}		_	7.5		

6.4. Source-Drain Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	V _{DSF}	I _{DR} = 11.5 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	V _{DD} ≈ 640 V	_	330	_	ns
Reverse recovery charge	Q _{rr}	$I_{DR} = 5.8 \text{ A}, V_{GS} = 0 \text{ V}$ -dI _{DR} /dt = 100 A/us	_	3.6	_	μС
Peak reverse recovery current	Irr	αι _{DR} /αι = 100 Α/μs	_	22	_	Α
Diode dv/dt ruggedness	dv/dt	$V_{DS} \le 640 \text{ V}, I_{DR} \le 5.8 \text{ A}, V_{GS} = 0 \text{ V}$	4.5	_	_	V/ns



7. Marking

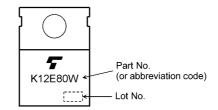


Fig. 7.1 Marking



8. Characteristics Curves (Note)

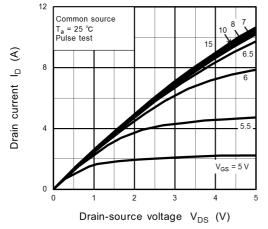
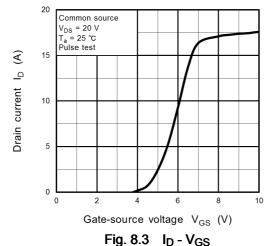


Fig. 8.1 I_D - V_{DS}



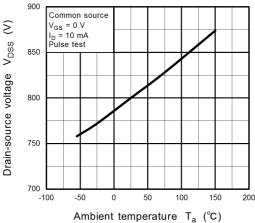


Fig. 8.5 V_{DSS} - T_a

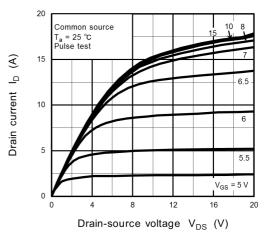


Fig. 8.2 I_D - V_{DS}

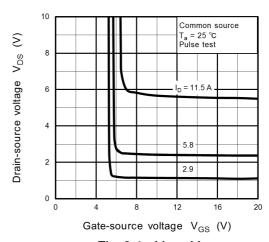


Fig. 8.4 V_{DS} - V_{GS}

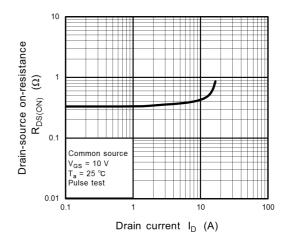


Fig. 8.6 R_{DS(ON)} - I_D

Drain-source on-resistance

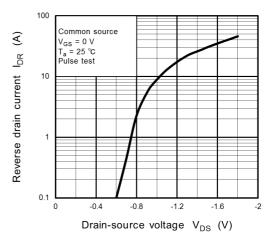
 $R_{\text{DS}(\text{ON})} \ \Omega^{12}$

0.5

0

-80

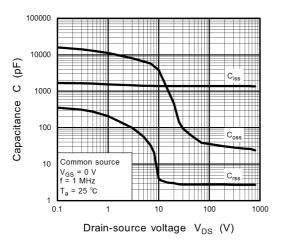
Common source V_{GS} = 10 V Pulse test



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Fig. 8.7 R_{DS(ON)} - T_a

Fig. 8.8 I_{DR} - V_{DS}



Ambient temperature T_a (°C)

Fig. 8.9 C - V_{DS}

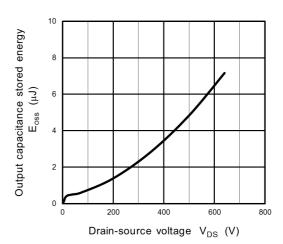


Fig. 8.10 Eoss - VDS

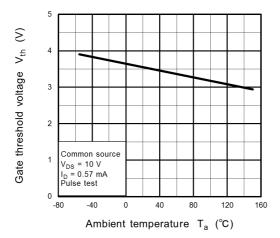


Fig. 8.11 V_{th} - T_a

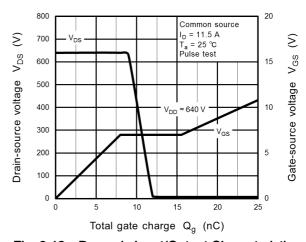


Fig. 8.12 Dynamic Input/Output Characteristics

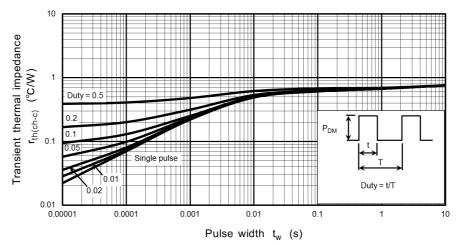


Fig. 8.13 r_{th} - t_w (Guaranteed Maximum)

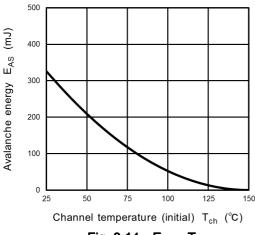


Fig. 8.14 E_{AS} - T_{ch} (Guaranteed Maximum)

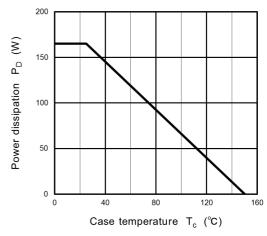
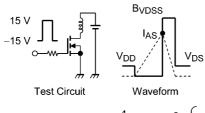


Fig. 8.15 P_D - T_c (Guaranteed Maximum)



 $R_G = 25 \Omega$, $V_{DD} = 90 V$ $E_{AS} = \frac{1}{2} \cdot L \cdot I_{AS}^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}}\right)$

Fig. 8.16 Test Circuit/Waveform

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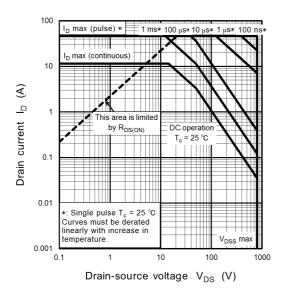


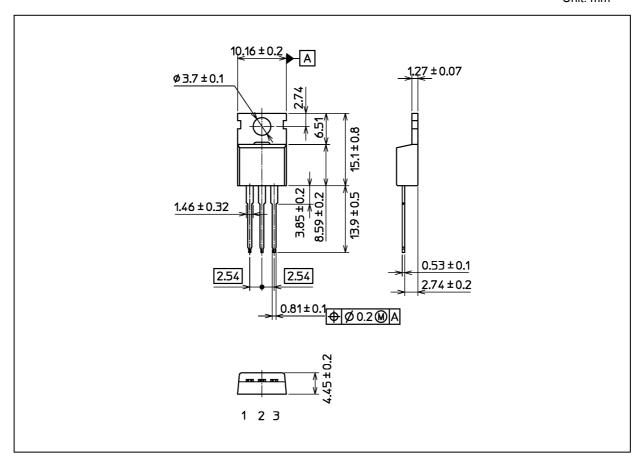
Fig. 8.17 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



Weight: 1.93 g (typ.)

	Package Name(s)
TOSHIBA: 2-10X1A	
Nickname: TO-220	



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